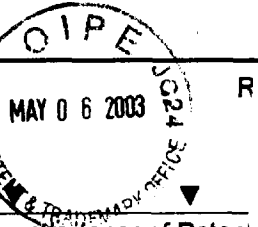


FORM PTO-1585 (Modified)
(Rev. 03-01)
OMB No. 0051-0027 (exp. 5/31/2002)
P06/REV03



05-13-2003

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office



102446575

Tab settings

To the Honorable Commissioner of Patent

Attached original documents or copy thereof.

1. Name of conveying party(ies):
Wolfgang Bergner
Linda Chen
Stephan Kudelka

5-6-03

2. Name and address of receiving party(ies):

Name: Infineon Technologies North America Corp.

Internal Address:

Street Address: 1730 First Street

City: San Jose State: CA ZIP: 95112

Additional names(s) of conveying party(ies) attached? Yes No

Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other

Execution Date: 04-14-03, 04-15-03, 04-14-03

4. Application number(s) or patent numbers(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.
10/248,841

HEREBY CERTIFY THAT THIS CORRESPONDENCE IS
BEING DEPOSITED WITH THE UNITED STATES POSTAL
SERVICE AS FIRST CLASS MAIL IN AN ENVELOPE AD-
DRESSED TO: COMMISSIONER OF PATENTS AND TRADE-
MARKS, WASHINGTON, D.C. 20231, ON

B. Patent No.(s)

DATE OF DEPOSIT: 5/2/03
K.C. ING-MARS
NAME OF PERSON MAKING DEPOSIT: Karen C. Li
SIGNATURE AND DATE

Additional name(s) & address(es) attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Todd M. C. Li

Internal Address:



32074

PATENT TRADEMARK OFFICE

Street Address:

05/12/2003 6TOM11 00000088 090458 10248841

01 FC:8021

40.00 CH

City:

State:

ZIP:

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41):.....\$ 40.00

- Enclosed - Any excess or insufficiency should be credited or debited to deposit account
- Authorized to be charged to deposit account

8. Deposit account number:

09-0458 FI 170

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Todd M. C. Li, Reg. No. 45,554

Todd M. C. Li

5/2/03

Name of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments, and document: 3

Docket No. FIS920020208US1

ASSIGNMENT

WHEREAS, we

Wolfgang Bergner of ~~70 Stagecoach Pass, Stormville, New York 12582;~~

and

*DARWIN STR. 7A, 01109 DRESDEN, GERMANY***Linda A. Chen** of 29F Surrey Lane, Wappingers Falls, New York 12590;

and

Stephan Kudelka of ~~463 Van Wyck Lake Rd., Fishkill, New York 12590;~~*Robinich str. 34, 01458 Ottendorf-Okrilla, Germany*

have invented certain improvements in

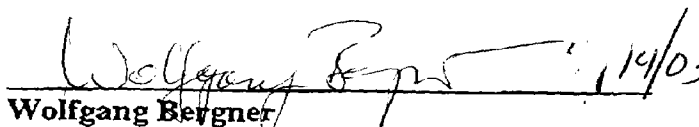
Process to Suppress Lithography at a Wafer Edge

Whereas, **INFINEON TECHNOLOGIES NORTH AMERICA CORP.**, having a place of business at 1730 First Street, San Jose, California 95112, (hereinafter called Assignee), desires to acquire the entire, right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, We, the above named, hereby sell, assign and transfer to Assignee, its successors and assigns, the entire right, title and interest in the said application and the invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and We request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to Assignee, its successors and assigns; and We hereby agree that Assignee may apply for foreign Letters Patent on said invention and We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by Assignee.

Signed:

(1)



 Wolfgang Bergner

and

(2)

 Linda A. Chen

and

(3)



 Stephan Kudelka

ASSIGNMENT

WHEREAS, we

Wolfgang Bergner of 70 Stagecoach Pass, Stormville, New York 12582;
and

Linda A. Chen of 29F Surrey Lane, Wappingers Falls, New York 12590;
and

Stephan Kudelka of 463 Van Wyck Lake Rd., Fishkill, New York 12590;

have invented certain improvements in

Process to Suppress Lithography at a Wafer Edge

Whereas, **INFINEON TECHNOLOGIES NORTH AMERICA CORP.**, having a place of business at 1730 First Street, San Jose, California 95112, (hereinafter called Assignee), desires to acquire the entire, right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, We, the above named, hereby sell, assign and transfer to Assignee, its successors and assigns, the entire right, title and interest in the said application and the invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and We request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to Assignee, its successors and assigns; and We hereby agree that Assignee may apply for foreign Letters Patent on said invention and We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by Assignee.

Signed:

(1)

Wolfgang Bergner

and

Xiaolin Chen 04/15/2003

X. **Linda A. Chen**

(2)

and

(3)

Stephan Kudelka

PATENT